

# Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-40	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-40	V
Emitter-Base Voltage	V <sub>EBO</sub>	-5	V
Base Current	I <sub>B</sub>	-500	mA
Continuous Collector Current	I <sub>C</sub>	-2	A
Peak Pulse Collector Current	Ісм	-4	A

# Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
Power Dissipation	(Note 5)		1.1 8.8	W	
Linear Derating Factor	(Note 6)	P <sub>D</sub>	1.7 13.6	mW/°C	
Thermal Resistance, Junction to Ambient	(Note 5)	D	113	°C/W	
	(Note 6)	− R <sub>θJA</sub>	73		
Thermal Resistance, Junction to Lead	(Note 7)	$R_{ heta JL}$	18.61		
Operating and Storage Temperature Range		T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

### ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes:

<sup>5.</sup> For a device mounted with collector leads on 25mm x 25mm 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.

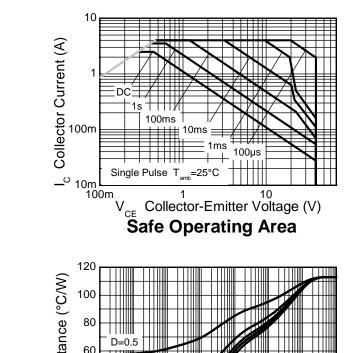
<sup>6.</sup> Same as Note 5, except the device is measured at  $t \le 5$  seconds.

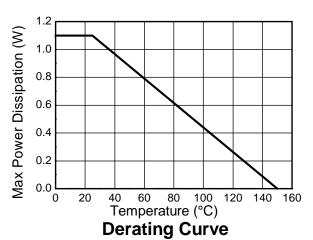
<sup>7.</sup> Thermal resistance from junction to solder-point (at the end of the collector leads).

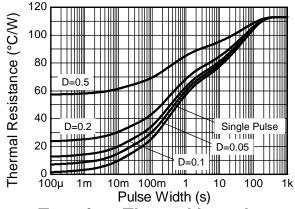
8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



### **Thermal Characteristics and Derating Information**







**Transient Thermal Impedance** 



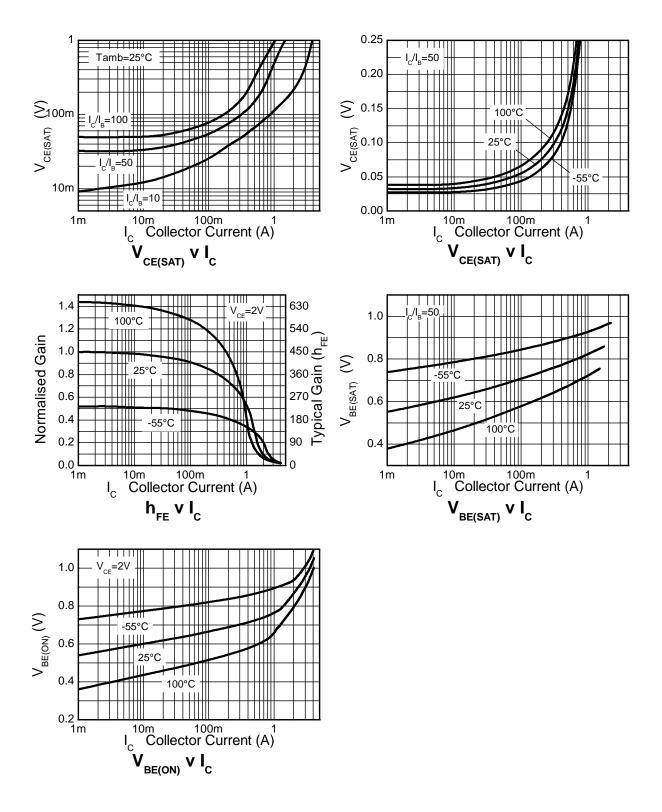
# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-40	-80		V	$I_{C} = -100 \mu A$
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	-40	-70	_	V	I <sub>C</sub> = -10mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-5	-8.8	_	V	I <sub>E</sub> = -100μA
Collector-Base Cut-Off Current	I <sub>CBO</sub>	_	_	-100	nA	$V_{CB} = -35V$
Emitter Cut-Off Current	I <sub>EBO</sub>	_	_	-100	nA	$V_{EB} = -4V$
Collector-Emitter Cut-Off Current	I <sub>CES</sub>		_	-100	nA	V <sub>CES</sub> = -35V
ON CHARACTERISTICS (Note 9)						
		300	480	_		$I_C = -10mA$ , $V_{CE} = -2V$
		300	450	_		$I_C = -100 \text{mA}, V_{CE} = -2 \text{V}$
DC Current Gain	h <sub>FE</sub>	180	290	_		$I_C = -1A$ , $V_{CE} = -2V$
		60	130	_		$I_C = -1.5A, V_{CE} = -2V$
		12	22	_		$I_C = -3A$ , $V_{CE} = -2V$
	V <sub>CE</sub> (sat)	_	-25	-40		I <sub>C</sub> = -100mA, I <sub>B</sub> = -10mA
		_	-150	-220		I <sub>C</sub> = -1A, I <sub>B</sub> = -100mA
Collector-Emitter Saturation Voltage		_	-195	-300		$I_C = -1.5A$ , $I_B = -100mA$
			-210	-300		$I_C = -2A$ , $I_B = -200mA$
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	_	-0.95	-1.0	V	I <sub>C</sub> = -2A, I <sub>B</sub> = -200mA
Base-Emitter Turn-On Voltage	V <sub>BE(on)</sub>	_	-0.85	-0.95	V	I <sub>C</sub> = -2A, V <sub>CE</sub> = -2V
SMALL SIGNAL CHARACTERISTICS						
Current Gain-Bandwidth Product	f <sub>T</sub>	150	190	_	MHz	$V_{CE} = -10V$ , $I_{C} = -50mA$ , $f = 100MHz$
Output Capacitance	C <sub>obo</sub>	_	19	25	pF	V <sub>CB</sub> = -10V, f = 1MHz
Turn-On Time	t <sub>(on)</sub>		40		ns	V <sub>CC</sub> = -15V, I <sub>C</sub> = -0.75A
Turn-Off Time	t <sub>(off)</sub>	_	435	_	ns	$I_{B1} = I_{B2} = -15\text{mA}$

Note: 9. Measured under pulsed conditions; pulse width  $\leq 300 \mu s$ , duty cycle  $\leq 2\%$ .



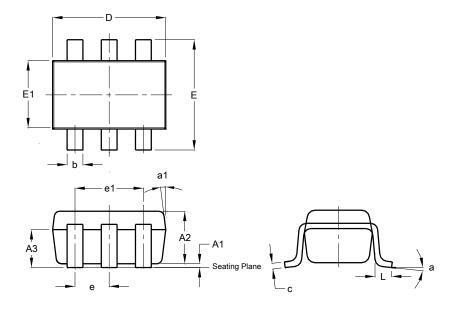
### Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)





## **Package Outline Dimensions**

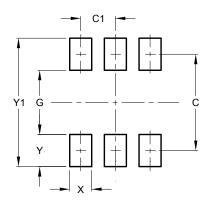
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT26					
Dim	Min	Max	Тур		
A1	0.013	0.10	0.05		
A2	1.00	1.30	1.10		
А3	0.70	0.80	0.75		
b	0.35	0.50	0.38		
С	0.10	0.20	0.15		
D	2.90	3.10	3.00		
е	-	-	0.95		
e1	-	-	1.90		
Е	2.70	3.00	2.80		
E1	1.50	1.70	1.60		
L	0.35	0.55	0.40		
а	-	-	8°		
a1	-	-	7°		
All Dimensions in mm					

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
Х	0.55
Y	0.80
Y1	3.20



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